

The MM60 series is a module socket compatible to specifications standardized in the PCI-SIG

Features

- Compatible to PCI Express Mini Card Electromechanical SPEC and can be used for connection with PCI Express and modules for USB transmission.
- Available with fixing latch for the whole connector and module. Latch will have operating portion on both ends for module ejection.
- Two types of module mounting heights are developed. Stand-off product is able to compile items under 1.8mm lower module compile height.
- Connector and latch are compatible to automatic mounting. Packing form is an embossed tape.

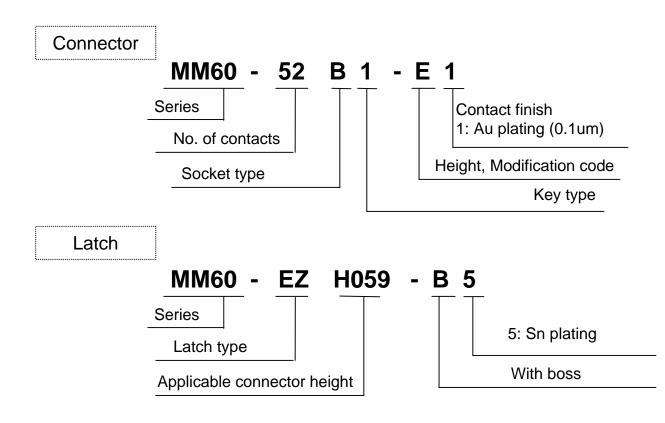
General Specifications

- •No. of contacts: 52 pos.
- •Contact resistance: 55m ohm max. (initial)
- •Dielectric withstanding voltage: AC 300Vr.m.s (per minute)
- •Operating temperature: -40 to+80 Deg. C
- •Rated Current: 0.5A per pin
- •Life time: 50 times
- •Insertion loss:-1dB min.(1.25Ghz max.)/-5dB min.(3.75Ghz max.)
- •Return loss:-12dBmax.(1.3GHz max.)/-7dB max.(2Ghz max.)-4dB(3.75GHz max.)
- •Cross talk(near end): -32dB max.(1.25Ghz max.)/-26dBmax.(3.75Ghz max.)

Materials and Finishes

Components	Materials/ Finishes	
	Connector	
Contact	Copper alloy/ contact area: Au plating over Ni terminal area: Au flash over Ni	
Insulator	Heat resistant material (UL94V-0)	
Hold down	Copper alloy/ Sn plating	
	Latch	
Contact	Stainless steel/ Sn plating	
Insulator	Heat resistant material (UL94V-0)	

Ordering Information

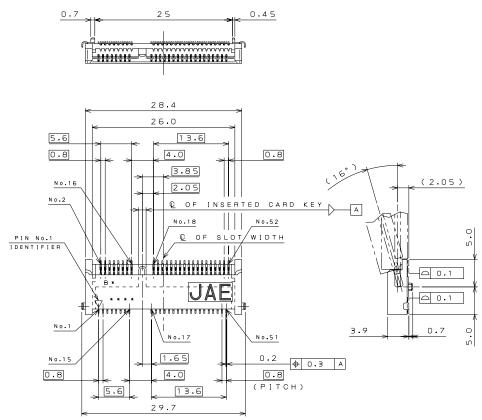


Combination

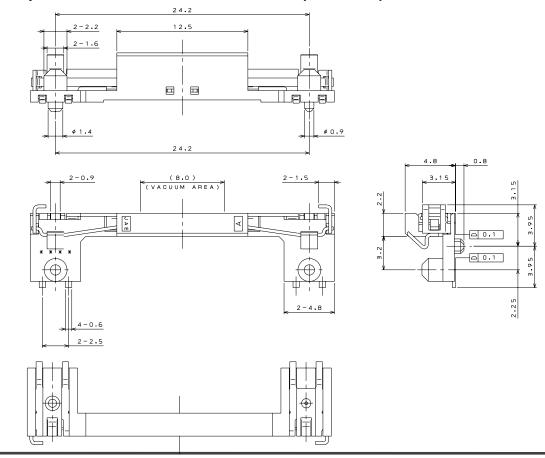
	Connector	Latch
Height 1	MM60-52B1-B2	MM60-EZH039-B5
Height 2	MM60-52B1-E1	MM60-EZH058-B5

Connector side: MM60-52B1-B2 (SJ105215)

Embossed Tape Product: MM60-52B1-B*-R600 (SJ105216)

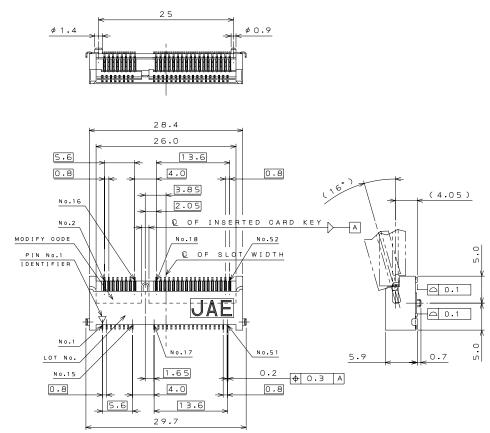


Latch side: MM60-EZH039-B5 (SJ105217) Embossed Tape Product: MM60-EZH039-B*-R600 (SJ105218)

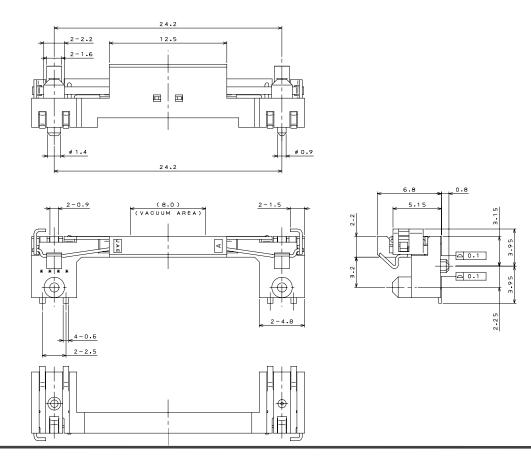


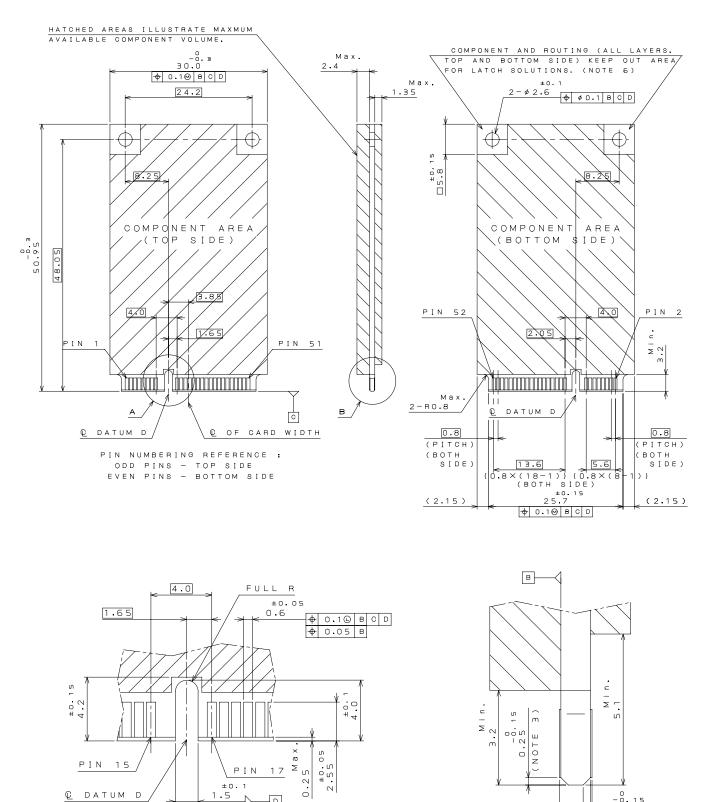
Connector side: MM60-52B1-E1 (SJ105219)

Embossed Tape Product: MM60-52B1-E*-R500 (SJ105220)



Latch side: MM60-EZH058-B5 (SJ105221) Embossed Tape Product: MM60-EZH058-B*-R500 (SJ105222)





Applicable Module Dimensions (for reference)

±0.1

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D

1.5

DETAIL A

C DATUM D

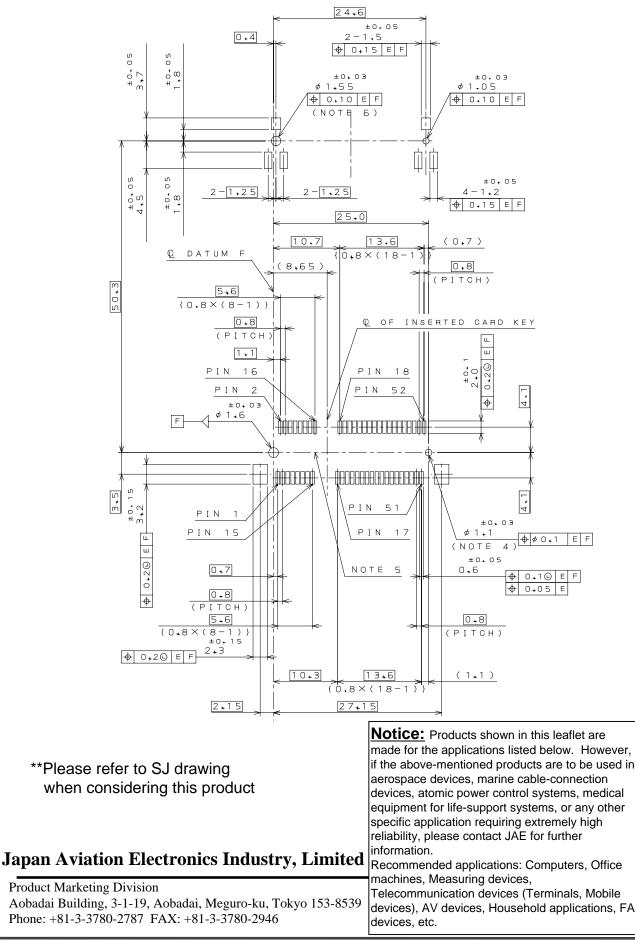
-0.15

t1.0

±0.1

0.25

DETAIL B



Applicable dimensions of board (for reference)

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